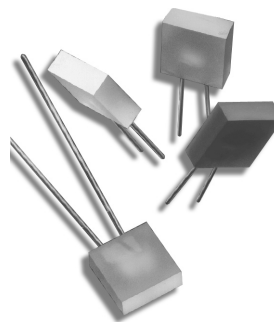


HLMP-R100, HLMP-0301, HLMP-0401, HLMP-0504

2.5 mm x 7.6 mm Rectangular LED Lamps



Data Sheet



Description

The HLMP-R100, -0301, -0401, -0504 are solid state lamps encapsulated in a radial lead rectangular epoxy package. They utilize a tinted, diffused epoxy to provide high on-off contrast and a flat high intensity emitting surface. Borderless package design allows creation of uninterrupted light emitting areas.

The HLMP-R100 uses a double heterojunction (DH) absorbing substrate (AS) aluminum gallium arsenide (AlGaAs) red LED chip in a light red epoxy package. This combination produces outstanding light output over a wide range of drive currents.

The HLMP-0301 has a high efficiency red GaAsP on GaP LED chip in a light red epoxy package.

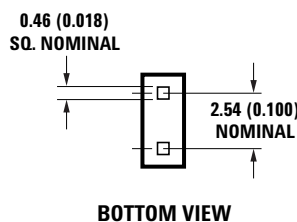
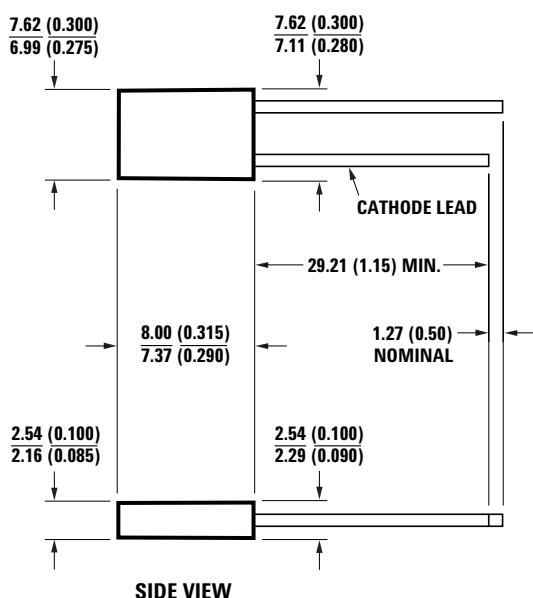
The HLMP-0401 provides a yellow GaAsP on GaP LED chip in a yellow epoxy package.

The HLMP-0504 provides a green GaP LED chip in a green epoxy package.

Features

- Rectangular light emitting surface
- Flat high sterance emitting surface
- Stackable on 2.54 mm (0.100 inch) centers
- Ideal as flush mounted panel indicators
- Ideal for backlighting legends
- Long life: solid state reliability
- Choice of 4 bright colors
 - DH AS AlGaAs Red
 - High Efficiency Red
 - Yellow
 - High Performance Green
- IC compatible/low current requirements

Package Dimensions



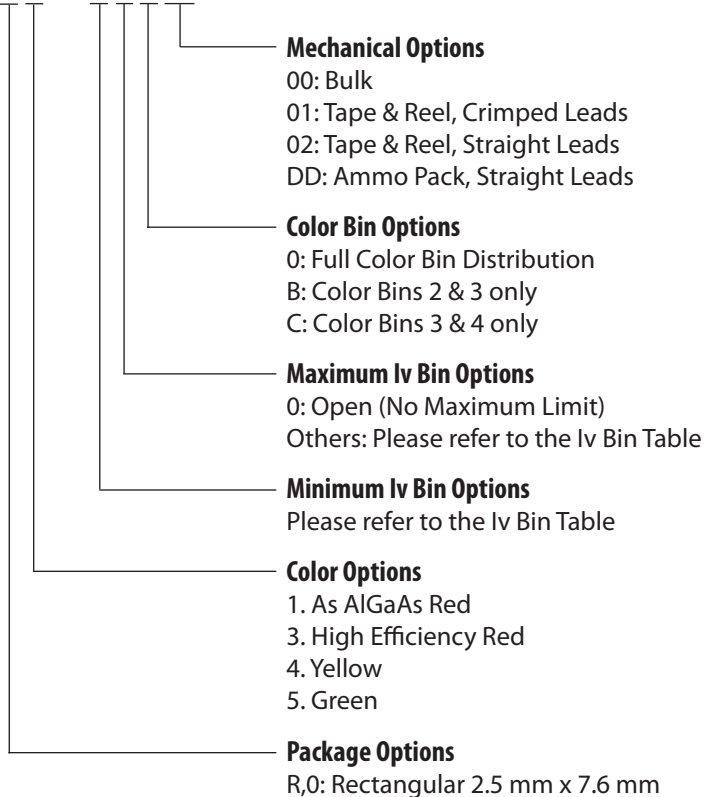
- NOTES:
1. ALL DIMENSIONS ARE IN MILLIMETERS (INCHES).
 2. AN EPOXY MENISCUS MAY EXTEND ABOUT 1 mm (0.040") DOWN THE LEADS.
 3. THERE IS A MAXIMUM 1° TAPER FROM BASE TO THE TOP OF LAMP.

Selection Guide

| Color | Part Number | Luminous Intensity Iv (mcd) at 20 mA | |
|---------------|-----------------|---|------|
| | | Min. | Typ. |
| DH AlGaAs Red | HLMP-R100 | 2.1 | – |
| | HLMP-R100-FG0xx | 5.4 | 17.2 |
| Red | HLMP-0301 | 2.1 | – |
| | HLMP-0301-C00xx | 1.3 | – |
| | HLMP-0301-DECxx | 2.1 | 6.8 |
| | HLMP-0301-CD0xx | 1.3 | 4.2 |
| Yellow | HLMP-0401 | 3.6 | – |
| | HLMP-0401-B00xx | 1.4 | – |
| | HLMP-0401-D00xx | 3.6 | – |
| | HLMP-0401-CD0xx | 2.2 | 7.2 |
| | HLMP-0401-DEBxx | 3.6 | 11.4 |
| Green | HLMP-0504 | 2.6 | – |
| | HLMP-0504-B00xx | 1.6 | – |
| | HLMP-0504-DECxx | 4.2 | 13.4 |
| | HLMP-0504-CD0xx | 2.6 | 8.4 |
| | HLMP-0504-C00xx | 2.6 | – |

Part Numbering System

HLMP - x x xx - x x x xx



Absolute Maximum Ratings at $T_A = 25^\circ\text{C}$

| Parameter | HLMP-R100 | HLMP-0301 | HLMP-0401 | HLMP-0504 | Units |
|---|-------------|-------------|-------------|-------------|------------------|
| Peak Forward Current | 300 | 90 | 60 | 90 | mA |
| Average Forward Current ^[1] | 20 | 25 | 20 | 25 | mA |
| DC Current ^[2] | 30 | 30 | 20 | 30 | mA |
| Power Dissipation | 87 | 135 | 85 | 135 | mW |
| Reverse Voltage ($I_R = 100 \mu\text{A}$) | 5 | 5 | 5 | 5 | V |
| Transient Forward Current ^[3] (10 μs Pulse) | 500 | 500 | 500 | 500 | mA |
| Operating Temperature Range | -20 to +100 | -40 to +100 | -40 to +100 | -20 to +100 | $^\circ\text{C}$ |
| Storage Temperature Range | -40 to +100 | -40 to +100 | -40 to +100 | -40 to +100 | |

Notes:

1. See Figure 5 to establish pulsed operating conditions.
2. For AlGaAs Red, Red, and Green Series derate linearly from 50°C at $0.5 \text{ mA}/^\circ\text{C}$. For Yellow Series derate linearly from 50°C at $0.2 \text{ mA}/^\circ\text{C}$.
3. The transient peak current is the maximum non-recurring peak current that can be applied to the device without damaging the LED die and wirebond. It is not recommended that the device be operated at peak current beyond the peak forward current listed in the Absolute Maximum Ratings.

Electrical/Optical Characteristics at $T_A = 25^\circ\text{C}$

| Sym. | Description | HLMP-R100 | | HLMP-0301 | | HLMP-0401 | | HLMP-0504 | | Units | Test Conditions | | | |
|-----------------------|---|-----------|------|-----------|------|-----------|------|-----------|------|-------|-----------------|------|---------------------------|----------------------------|
| | | Min. | Typ. | Max. | Min. | Typ. | Max. | Min. | Typ. | | | Max. | Min. | Typ. |
| $2\theta_{1/2}$ | Included Angle Between Half Luminous Intensity Points | | 100 | | | 100 | | | 100 | | | | Deg. | Note 1. Fig. 6 |
| λ_p | Peak Wavelength | | 645 | | | 635 | | | 583 | | | | nm | Measurement at Peak |
| λ_d | Dominant Wavelength | | 637 | | | 626 | | | 585 | | | | nm | Note 2. |
| $\Delta\lambda_{1/2}$ | Spectral Line Halfwidth | | 20 | | | 40 | | | 36 | | | | nm | |
| τ_s | Speed of Response | | 30 | | | 90 | | | 90 | | | | ns | |
| C | Capacitance | | 30 | | | 16 | | | 18 | | | | pF | $V_F = 0$; $f = 1$ MHz |
| $R\theta_{J-PIN}$ | Thermal Resistance | | 260 | | | 260 | | | 260 | | | | $^\circ\text{C}/\text{W}$ | Junction to Cathode Lead |
| V_F | Forward Voltage | 1.8 | 2.2 | | 1.9 | 2.6 | | 2.1 | 2.6 | | 2.2 | 3.0 | V | $I_F = 20$ mA Figure 2. |
| V_R | Reverse Breakdown Voltage | 5.0 | | 5.0 | | 5.0 | | 5.0 | | 5.0 | | | V | $I_R = 100$ μA |
| η_v | Luminous Efficacy | | 80 | | | 145 | | | 500 | | | | lm/W | Note 3. |

Notes:

- $\theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- The dominant wavelength, λ_d , is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- Radiant intensity, I_e , in watts/steradian, may be found from the equation $I_e = I_v/\eta_v$, where I_v is the luminous intensity in candelas and η_v is the luminous efficacy in lumens/watt.

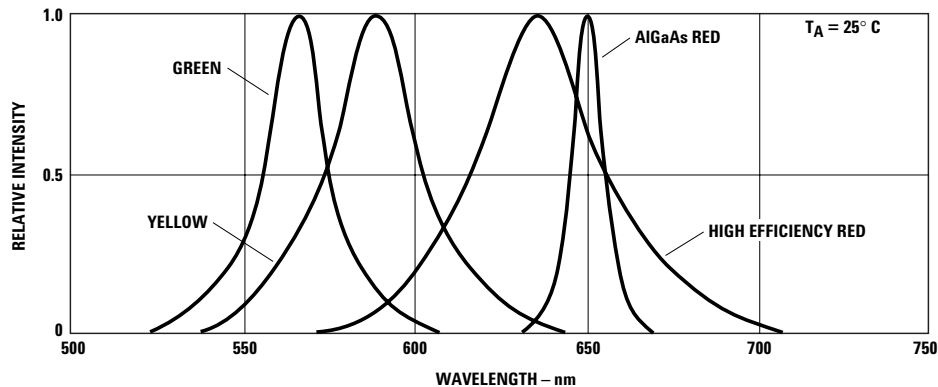


Figure 1. Relative intensity vs. wavelength.

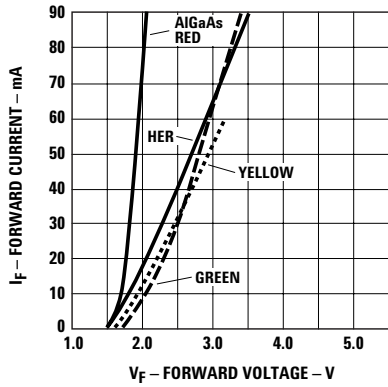


Figure 2. Forward current vs. forward voltage. V_F (300 mA) for AlGaAs Red = 2.6 volts typical.

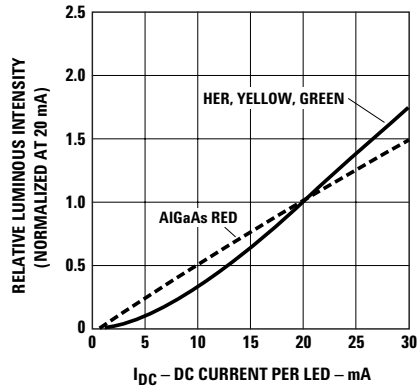


Figure 3. Relative luminous intensity vs. forward current.

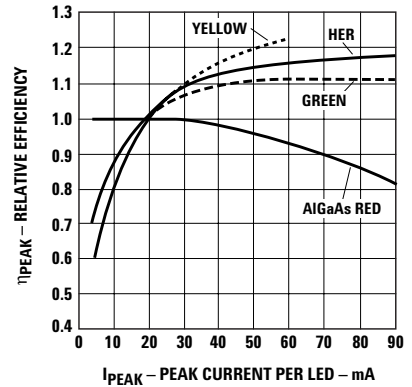


Figure 4. Relative efficiency (luminous intensity per unit current) vs. peak current. η_V (300 mA) for AlGaAs Red = 0.7.

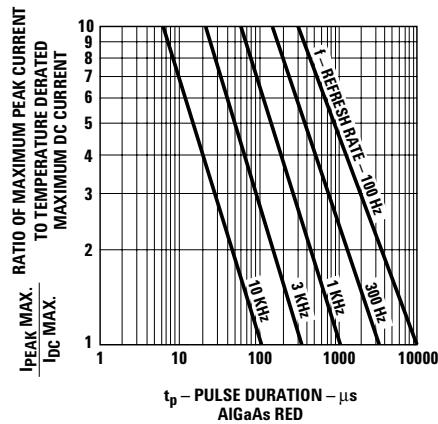
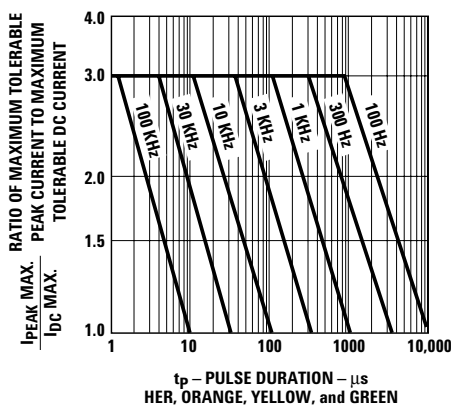


Figure 5. Maximum tolerable peak current vs. peak duration ($I_{PEAK MAX}$ determined from temperature derated $I_{DC MAX}$).

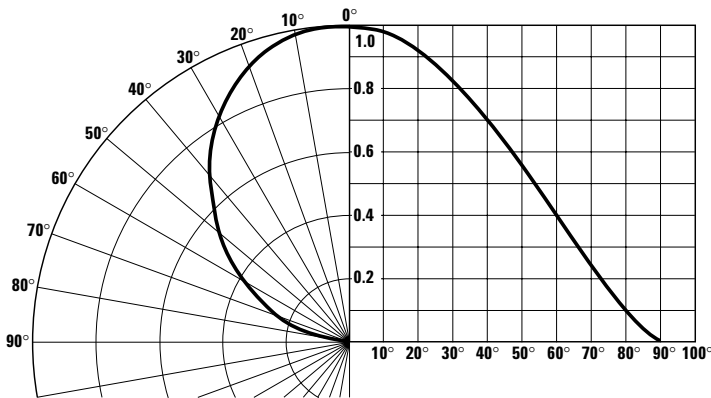


Figure 6. Relative luminous intensity vs. angular displacement.

Intensity Bin Limits

| Color | Bin | Intensity Range (mcd) | |
|-------|---------|-----------------------|--------|
| | | Min. | Max. |
| Red | C | 0.5 | 2.4 |
| | D | 2.4 | 3.8 |
| | E | 3.8 | 6.1 |
| | F | 6.1 | 9.7 |
| | G | 9.7 | 15.5 |
| | H | 15.5 | 24.8 |
| | I | 24.8 | 39.6 |
| | J | 39.6 | 63.4 |
| | K | 63.4 | 101.5 |
| | L | 101.5 | 162.4 |
| | M | 162.4 | 234.6 |
| | N | 234.6 | 340.0 |
| | O | 340.0 | 540.0 |
| | P | 540.0 | 850.0 |
| | Q | 850.0 | 1200.0 |
| | R | 1200.0 | 1700.0 |
| | S | 1700.0 | 2400.0 |
| | T | 2400.0 | 3400.0 |
| | U | 3400.0 | 4900.0 |
| | V | 4900.0 | 7100.0 |
| W | 7100.0 | 10200.0 | |
| X | 10200.0 | 14800.0 | |
| Y | 14800.0 | 21400.0 | |
| Z | 21400.0 | 30900.0 | |

Maximum tolerance for each bin limit is $\pm 18\%$.

Intensity Bin Limits, continued

| Color | Bin | Intensity Range (mcd) | |
|--------|---------|-----------------------|---------|
| | | Min. | Max. |
| Yellow | B | 1.6 | 2.5 |
| | C | 2.5 | 4.0 |
| | D | 4.0 | 6.5 |
| | E | 6.5 | 10.3 |
| | F | 10.3 | 16.6 |
| | G | 16.6 | 26.5 |
| | H | 26.5 | 42.3 |
| | I | 42.3 | 67.7 |
| | J | 67.7 | 108.2 |
| | K | 108.2 | 173.2 |
| | L | 173.2 | 250.0 |
| | M | 250.0 | 360.0 |
| | N | 360.0 | 510.0 |
| | O | 510.0 | 800.0 |
| | P | 800.0 | 1250.0 |
| | Q | 1250.0 | 1800.0 |
| | R | 1800.0 | 2900.0 |
| | S | 2900.0 | 4700.0 |
| | T | 4700.0 | 7200.0 |
| | U | 7200.0 | 11700.0 |
| V | 11700.0 | 18000.0 | |
| W | 18000.0 | 27000.0 | |
| Green | B | 1.8 | 2.9 |
| | C | 2.9 | 4.7 |
| | D | 4.7 | 7.6 |
| | E | 7.6 | 12.0 |
| | F | 12.0 | 19.1 |
| | G | 19.1 | 30.7 |
| | H | 30.7 | 49.1 |
| | I | 49.1 | 78.5 |
| | J | 78.5 | 125.7 |
| | K | 125.7 | 201.1 |
| | L | 201.1 | 289.0 |
| | M | 289.0 | 417.0 |
| | N | 417.0 | 680.0 |
| | O | 680.0 | 1100.0 |
| | P | 1100.0 | 1800.0 |
| | Q | 1800.0 | 2700.0 |
| | R | 2700.0 | 4300.0 |
| | S | 4300.0 | 6800.0 |
| | T | 6800.0 | 10800.0 |
| | U | 10800.0 | 16000.0 |
| V | 16000.0 | 25000.0 | |
| W | 25000.0 | 40000.0 | |

Color Categories

| Color | Category# | Lambda (nm) | |
|--------|-----------|-------------|-------|
| | | Min. | Max. |
| Green | 6 | 561.5 | 564.5 |
| | 5 | 564.5 | 567.5 |
| | 4 | 567.5 | 570.5 |
| | 3 | 570.5 | 573.5 |
| | 2 | 573.5 | 576.5 |
| Yellow | 1 | 582.0 | 584.5 |
| | 3 | 584.5 | 587.0 |
| | 2 | 587.0 | 589.5 |
| | 4 | 589.5 | 592.0 |
| | 5 | 592.0 | 593.0 |

Tolerance for each bin limit is ± 0.5 nm.

Mechanical Option Matrix

| Mechanical Option Code | Definition |
|------------------------|---|
| 00 | Bulk Packaging, minimum increment 500 pcs/bag |
| 01 | Tape & Reel, crimped leads, minimum increment 1300 pcs/bag |
| 02 | Tape & Reel, straight leads, minimum increment 1300 pcs/bag |
| DD | Ammo Pack, straight leads with minimum increment 2K/pack |

Note:

All categories are established for classification of products. Products may not be available in all categories. Please contact your local Avago representative for further clarification/information.

Precautions

Lead Forming

- The leads of an LED lamp may be preformed or cut to length prior to insertion and soldering into PC board.
- If lead forming is required before soldering, care must be taken to avoid any excessive mechanical stress induced to LED package. Otherwise, cut the leads of LED to length after soldering process at room temperature. The solder joint formed will absorb the mechanical stress of the lead cutting from traveling to the LED chip die attach and wirebond.
- It is recommended that tooling made to precisely form and cut the leads to length rather than rely upon hand operation.

Soldering Conditions

- Care must be taken during PCB assembly and soldering process to prevent damage to LED component.
- The closest LED is allowed to solder on board is 1.59 mm below the body (encapsulant epoxy) for those parts without standoff.
- Recommended soldering conditions:

| | Wave Soldering | Manual Solder Dipping |
|----------------------|----------------|-----------------------|
| Pre-heat Temperature | 105°C Max. | – |
| Pre-heat Time | 30 sec Max. | – |
| Peak Temperature | 250°C Max. | 260°C Max. |
| Dwell Time | 3 sec Max. | 5 sec Max. |

- Wave soldering parameter must be set and maintained according to recommended temperature and dwell time in the solder wave. Customer is advised to periodically check on the soldering profile to ensure the soldering profile used is always conforming to recommended soldering condition.
- If necessary, use fixture to hold the LED component in proper orientation with respect to the PCB during soldering process.
- Proper handling is imperative to avoid excessive thermal stresses to LED components when heated. Therefore, the soldered PCB must be allowed to cool to room temperature, 25°C, before handling.
- Special attention must be given to board fabrication, solder masking, surface plating and lead holes size and component orientation to assure solderability.
- Recommended PC board plated through hole sizes for LED component leads:

| LED Component Lead Size | Diagonal | Plated Through Hole Diameter |
|--|--------------------------|--|
| 0.457 x 0.457 mm (0.018 x 0.018 inch) | 0.646 mm (0.025 inch) | 0.976 to 1.078 mm (0.038 to 0.042 inch) |
| 0.508 x 0.508 mm (0.020 x 0.020 inch) | 0.718 mm (0.028 inch) | 1.049 to 1.150 mm (0.041 to 0.045 inch) |

Note: Refer to application note AN1027 for more information on soldering LED components.

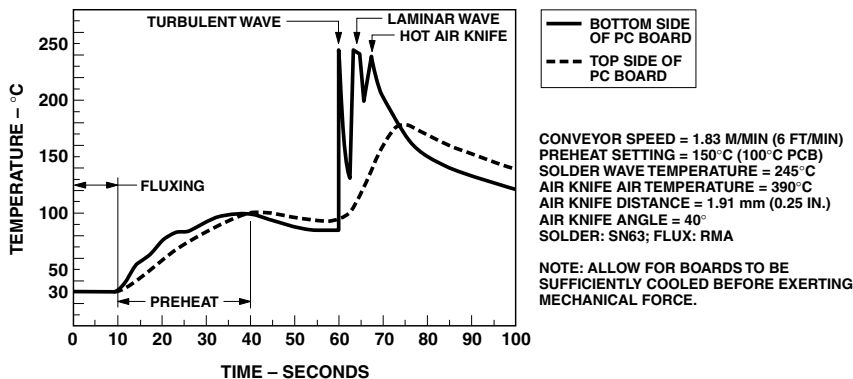


Figure 7. Recommended wave soldering profile.

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